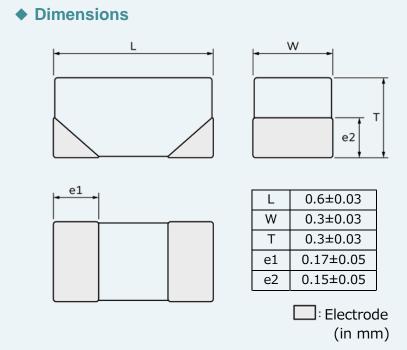


0201 Size, 0.33mm max. Thickness, BLH03HA_SN1 Series



Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	15000



Features

- 1. Horizontal winding inner coil structure enables low storage capacitance which result to high noise suppression performance.
- 2. The small size of BLH03 series (0.6x0.3mm) is suitable for noise suppression in small equipment such as cellular phones.





◆ Rated Value

■ Operating temperature range -40° to $+125^{\circ}$

■ Storage temperature range -40° C to $+125^{\circ}$ C

	Impedance (Ω) at 100 MHz	Rated current (mA)	DC resistance (Ω max.)	
Part Number			Initial value	Value after testing
BLH03HA400SN1	40±40%	150	2.2	2.3

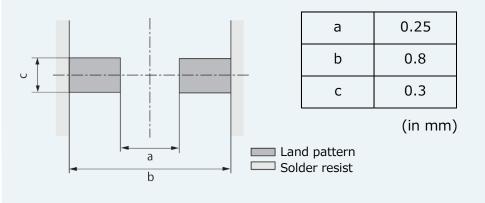
◆ Equivalent Circuits



(Resistance element becomes dominant at high frequencies.) no polarity

♦ Land Dimensions (Reflow soldering)

The following diagram shows the recommended land dimensions for reflow soldering.





0201 Size, 0.33mm max. Thickness, BLH03HA SN1 Series



Precautions on rating

Avoid using in exceeded the rated temperature range, rated voltage, or rated current. Usage when the ratings are exceeded could lead to wire breakage, burning, or other serious fault.

Inrush current

If an inrush current (or pulse current or rush current) that significantly exceeds the rated current is applied to the product, overheating could occur, resulting in wire breakage, burning, or other serious fault.

Corrosive gas

Please refrain from use since contact with environments with corrosive gases (sulfur gas [hydrogen sulfide, sulfur dioxide, etc.], chlorine, ammonia, etc.) or oils (cutting oil, silicone oil, etc.) that have come into contact with the previously stated corrosive gas environment will result in deterioration of product quality or an open from deterioration due to corrosion of product electrode, etc. We will not bear any responsibility for use under these environments.

Flux and solder used.

Flux	 Use a rosin-based flux. Do not use a highly acidic flux with a halide content exceeding 0.2(wt)% (chlorine conversion value). Do not use a water-soluble flux.
Solder	 Use Sn-3.0Ag-0.5Cu solder. Standard thickness of solder paste: 80 μm to 100 μm

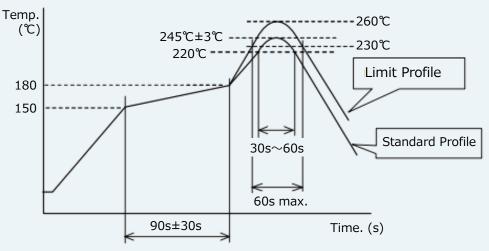
If you want to use a flux other than the above, please consult our technical department.





Soldering conditions (Reflow)

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 100°C max.
 - Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max. Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows. The excessive limit soldering conditions may cause leaching of the electrode and/or resulting in the deterioration of product quality.



	Standard profile	Limit profile
Pre-heating	150°C to 180°C/90 s±30 s	150°C to 180°C/90 s±30 s
Heating	Above 220°C/30 s to 60 s	Above 230°C/60 s max.
Peak temperature	245°C±3°C	260°C/10 s
Number of reflow cycles	2 times	2 times